

VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Claims:

Claims 8-11 have been cancelled.

Claim 12 has been amended as follows:

12. (Three Times Amended) A sensor comprising:

a first chip of semiconductor material;

a sensor element having a movable microstructure, the sensor element supported by the first chip and structured to generate a first signal in response to a movement of the microstructure relative to the first chip;

a second chip of semiconductor material covering the sensor element and configured to receive the first signal, the second chip of semiconductor material comprising a processing circuit formed therein and electrically coupled to the sensor element to receive the first signal, the processing circuit structured to process the first signal and generate a second signal based on the first signal; and

a wall formed on the first chip and surrounding the sensor element and connecting the first chip to the second chip, the wall defining a hermetically sealed chamber between the first chip and the second chip and enclosing the sensor element.